

Low-Power CK420BQ Derivative for PCIe Common Clock Architectures

DATASHEET

General Description

The 932SQL450 is a low power version of the CK420BQ synthesizer for Intel-based server platforms. It has 85-ohm LP-HCSL outputs allowing for direct connection to 85-ohm transmission lines. The 932SQL450 is driven with a 25MHz crystal for maximum performance. It generates CPU outputs of 100MHz. This device has a "low-drift" non-spread SAS/SRC PLL for use in systems that need to communicate across PCIe domains.

Recommended Application

Low Power CK420BQ w/Zout=85ohms or PCIe Common Clocked Systems (CC)

Key Specifications

- CPU, SRC, NS_SRC and NS_SAS cycle-cycle jitter <50ps
- Output to output skew <50ps
- Phase jitter: PCle Gen2 <2.5ps rms
- Phase jitter: PCle Gen3 <0.6ps rms
- Phase jitter: QPI <0.3ps rms
- Phase jitter: NS-SAS <1.3ps rms using long period phase jitter method

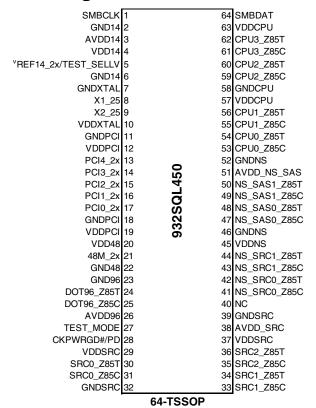
Features/Benefits

- Integrated 85 ohm differential terminations; saves 48 resistors and 82mm² area
- LP-HCSL output drivers; 40% typical power savings over 932SQ420
- 0.5% down spread capable on CPU, SRC and PCI outputs; reduce EMI
- Additional down spread amounts selectable via SMBus: maximal system flexibility
- 64-pin TSSOP and VFQFPN packages; smallest board footprint

Output Features

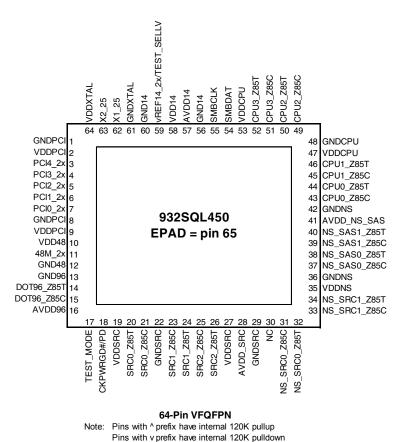
- 4 Low-Power HCSL-compatible (LP-HCSL) CPU outputs
- 2 LP-HCSL NS SAS outputs
- 2 LP-HCSL NS_SRC outputs
- 3 LP-HCSL SRC outputs
- 1 LP-HCSL DOT96 output
- 1 3.3V 48M output
- 5 3.3V PCI outputs
- 1 3.3V 14.318M output

Pin Configurations



Note: Pins with ^ prefix have internal 120K pullup Pins with v prefix have internal 120K pulldown

1





64TSSOP Pin Descriptions

PIN#	PIN NAME	TYPE	DESCRIPTION
1	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
2	GND14	PWR	Ground pin for 14MHz output and logic.
3	AVDD14	PWR	Analog power pin for 14MHz PLL
4	VDD14	PWR	Power pin for 14MHz output and logic
			14.318 MHz reference clock capable of driving 2 loads/ TEST_SEL latched input to enable test
5			mode. The TEST_SEL input is a low threshold input. See the Electrical Tables and the Test
			Clarification Table. This pin has a weak (~120Kohm) internal pull down.
6	GND14	PWR	Ground pin for 14MHz output and logic.
7	GNDXTAL		Ground pin for Crystal Oscillator.
8	X1_25		Crystal input, Nominally 25.00MHz.
9	X2_25		Crystal output, Nominally 25.00MHz.
10	VDDXTAL		3.3V power for the crystal oscillator.
11	GNDPCI		Ground pin for PCI outputs and logic.
12	VDDPCI		3.3V power for the PCI outputs and logic
13	PCI4_2x		3.3V PCI clock output capable of driving two loads.
14	PCI3_2x		3.3V PCI clock output capable of driving two loads.
15	PCI2_2x		3.3V PCI clock output capable of driving two loads.
16	PCI1_2x		3.3V PCI clock output capable of driving two loads.
17	PCI0_2x		3.3V PCI clock output capable of driving two loads.
18	GNDPCI		Ground pin for PCI outputs and logic.
19	VDDPCI		3.3V power for the PCI outputs and logic
20	VDD48		3.3V power for the 48MHz output and logic
21	48M_2x		3.3V 48MHz output capable of driving 2 loads.
22	GND48		Ground pin for 48MHz output and logic.
23	GND96		Ground pin for DOT96 output and logic.
			True clock of low-power push-pull differential 96MHz output. Internally terminated to drive 85ohm
24	DOT96_Z85T	OUT	transmission lines with no external components.
			Complementary clock of low-power push-pull differential 96MHz output. Internally terminated to
25	DOT96_Z85C	OUT	drive 850hm transmission lines with no external components.
26	AVDD96	PWR	3.3V power for the 48/96MHz PLL and the 96MHz output and logic
20	A V DD90	FVVI	TEST_MODE is a real time input to select between Hi-Z and REF/N divider mode while in test
27	TEST_MODE	IN	mode. Refer to Test Clarification Table.
			CKPWRGD# is an active low input used to sample latched inputs and allow the device to Power
28	CKPWRGD#/PD	IN	
20	CKPWhGD#/PD	IIN	Up. PD is an asynchronous active high input pin used to put the device into a low power state.
-00	VDDCDC	DWD	The internal clocks and PLLs are stopped.
29	VDDSRC	PWR	3.3V power for the SRC outputs and logic
30	SRC0_Z85T	OUT	True clock of low-power push-pull differential SRC output. Internally terminated to drive 85ohm
			transmission lines with no external components.
31	SRC0_Z85C	OUT	Complementary clock of low-power push-pull differential SRC output. Internally terminated to
		DIME	drive 85ohm transmission lines with no external components.
32	GNDSRC	PWR	Ground pin for SRC outputs and logic.
33	SRC1_Z85C	OUT	Complementary clock of low-power push-pull differential SRC output. Internally terminated to
	_		drive 85ohm transmission lines with no external components.
34	SRC1_Z85T	OUT	True clock of low-power push-pull differential SRC output. Internally terminated to drive 85ohm
			transmission lines with no external components.
35	SRC2_Z85C	OUT	Complementary clock of low-power push-pull differential SRC output. Internally terminated to
		ļ - - -	drive 85ohm transmission lines with no external components.
36	SRC2_Z85T	OUT	True clock of low-power push-pull differential SRC output. Internally terminated to drive 85ohm
			transmission lines with no external components.
37	VDDSRC		3.3V power for the SRC outputs and logic
38	AVDD_SRC		3.3V power for the SRC PLL analog circuits
39	GNDSRC		Ground pin for SRC outputs and logic.
40	NC	N/A	No Connection.



64TSSOP Pin Descriptions (cont.)

PIN#	PIN NAME	TYPE	DESCRIPTION
			Complementary clock of low-power push-pull differential non-spreading SRC output. Internally
41	NS_SRC0_Z85C	OUT	terminated to drive 85ohm transmission lines with no external components.
40	NC CDC0 70FT	OUT	True clock of low-power push-pull differential non-spreading SRC output. Internally terminated to
42	NS_SRC0_Z85T		drive 85ohm transmission lines with no external components.
43	NO 0004 7050		Complementary clock of low-power push-pull differential non-spreading SRC output. Internally
43	NS_SRC1_Z85C	OUT	terminated to drive 85ohm transmission lines with no external components.
44	NS_SRC1_Z85T	OUT	True clock of low-power push-pull differential non-spreading SRC output. Internally terminated to
44	NS_SNC1_2831	001	drive 85ohm transmission lines with no external components.
45	VDDNS	PWR	3.3V power for the Non-Spreading differential outputs outputs and logic
46	GNDNS	PWR	Ground pin for non-spreading differential outputs and logic.
47	NS_SAS0_Z85C	OUT	Complementary clock of low-power push-pull differential non-spreading SAS output. Internally
47	NS_SASU_283C	001	terminated to drive 85ohm transmission lines with no external components.
48	NS_SAS0_Z85T	OUT	True clock of low-power push-pull differential non-spreading SAS output. Internally terminated to
40	NS_SASU_2831	001	drive 85ohm transmission lines with no external components.
49	NS_SAS1_Z85C	OUT	Complementary clock of low-power push-pull differential non-spreading SAS output. Internally
43	10_0401_200		terminated to drive 85ohm transmission lines with no external components.
50	NS_SAS1_Z85T		True clock of low-power push-pull differential non-spreading SAS output. Internally terminated to
30			drive 85ohm transmission lines with no external components.
51	AVDD_NS_SAS	PWR	3.3V power for the non-spreading SAS/SRC PLL analog circuits.
52	GNDNS		Ground pin for non-spreading differential outputs and logic.
53	CPU0_Z85C OUT		Complementary clock of low-power push-pull differential CPU output. Internally terminated to
30	01 00_2000		drive 85ohm transmission lines with no external components.
54	CPU0_Z85T	1 ()	True clock of low-power push-pull differential CPU output. Internally terminated to drive 85ohm
54	01 00_2001		transmission lines with no external components.
55	CPU1_Z85C	1 ()	Complementary clock of low-power push-pull differential CPU output. Internally terminated to
- 00			drive 85ohm transmission lines with no external components.
56	CPU1_Z85T	1 ()	True clock of low-power push-pull differential CPU output. Internally terminated to drive 85ohm
- 00			transmission lines with no external components.
57	VDDCPU		3.3V power for the CPU outputs and logic
58	GNDCPU		Ground pin for CPU outputs and logic.
59			Complementary clock of low-power push-pull differential CPU output. Internally terminated to
00	CPU2_Z85C		drive 85ohm transmission lines with no external components.
60	CPU2_Z85T		True clock of low-power push-pull differential CPU output. Internally terminated to drive 85ohm
		001	transmission lines with no external components.
61	CPU3_Z85C	OUT	Complementary clock of low-power push-pull differential CPU output. Internally terminated to
			drive 85ohm transmission lines with no external components.
62	CPU3_Z85T		True clock of low-power push-pull differential CPU output. Internally terminated to drive 85ohm
			transmission lines with no external components.
63	VDDCPU		3.3V power for the CPU outputs and logic
64	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant



64VFQFPN Pin Descriptions

PIN#	PIN NAME	TYPE	DESCRIPTION					
	GNDPCI		Ground pin for PCI outputs and logic.					
	VDDPCI		3.3V power for the PCI outputs and logic					
	PCI4_2x	_	3.3V PCI clock output capable of driving two loads.					
	PCI3_2x		3.3V PCI clock output capable of driving two loads.					
-	PCI2_2x	_	3.3V PCI clock output capable of driving two loads.					
	PCI1_2x	_	3.3V PCI clock output capable of driving two loads.					
	PCI0_2x		3.3V PCI clock output capable of driving two loads.					
	GNDPCI		Ground pin for PCI outputs and logic.					
	VDDPCI		3.3V power for the PCI outputs and logic					
	VDD48		3.3V power for the 48MHz output and logic					
	48M_2x		3.3V 48MHz output capable of driving 2 loads.					
	 GND48		Ground pin for 48MHz output and logic.					
	GND96		Ground pin for DOT96 output and logic.					
			True clock of low-power push-pull differential 96MHz output. Internally terminated to drive					
14	DOT96_Z85T	OUT	85ohm transmission lines with no external components.					
			Complementary clock of low-power push-pull differential 96MHz output. Internally					
15	DOT96_Z85C	OUT	terminated to drive 850hm transmission lines with no external components.					
16	AVDD96	PWR	3.3V power for the 48/96MHz PLL and the 96MHz output and logic					
			TEST_MODE is a real time input to select between Hi-Z and REF/N divider mode while in					
17	TEST_MODE	IN	test mode. Refer to Test Clarification Table.					
			CKPWRGD# is an active low input used to sample latched inputs and allow the device to					
18	CKPWRGD#/PD	IN	Power Up. PD is an asynchronous active high input pin used to put the device into a low					
'0	CRPWAGD#/PD IN		ower state. The internal clocks and PLLs are stopped.					
19	VDDSRC	PWR	3.3V power for the SRC outputs and logic					
13	VDDONO		True clock of low-power push-pull differential SRC output. Internally terminated to drive					
20	SRC0_Z85T	OUT	85ohm transmission lines with no external components.					
			Complementary clock of low-power push-pull differential SRC output. Internally terminated					
21	SRC0_Z85C	OUT	to drive 85ohm transmission lines with no external components.					
22	GNDSRC	PWR	Ground pin for SRC outputs and logic.					
			Complementary clock of low-power push-pull differential SRC output. Internally terminated					
23	SRC1_Z85C	OUT	to drive 85ohm transmission lines with no external components.					
			True clock of low-power push-pull differential SRC output. Internally terminated to drive					
24	SRC1_Z85T	OUT	85ohm transmission lines with no external components.					
			Complementary clock of low-power push-pull differential SRC output. Internally terminated					
25	SRC2_Z85C	OUT	to drive 85ohm transmission lines with no external components.					
			True clock of low-power push-pull differential SRC output. Internally terminated to drive					
26	SRC2_Z85T	OUT	85ohm transmission lines with no external components.					
27	VDDSRC	PWR	3.3V power for the SRC outputs and logic					
	AVDD_SRC		3.3V power for the SRC PLL analog circuits					
29	GNDSRC		Ground pin for SRC outputs and logic.					
	NC		No Connection.					
			Complementary clock of low-power push-pull differential non-spreading SRC output.					
31	NS_SRC0_Z85C	OUT	Internally terminated to drive 850hm transmission lines with no external components.					
			True clock of low-power push-pull differential non-spreading SRC output. Internally					
32	NS_SRC0_Z85T	OUT	terminated to drive 850hm transmission lines with no external components.					
			Complementary clock of low-power push-pull differential non-spreading SRC output.					
33	NS_SRC1_Z85C	OUT						
			Internally terminated to drive 85ohm transmission lines with no external components. True clock of low-power push-pull differential non-spreading SRC output. Internally					
34	NS_SRC1_Z85T	OUT						
25	VDDNS	DWD	terminated to drive 85ohm transmission lines with no external components.					
35	VDDNS		3.3V power for the Non-Spreading differential outputs outputs and logic					
36	GNDNS	FVVK	Ground pin for non-spreading differential outputs and logic.					
38	NS_SAS0_Z85T	OUT	True clock of low-power push-pull differential non-spreading SAS output. Internally					
<u> </u>			terminated to drive 85ohm transmission lines with no external components.					

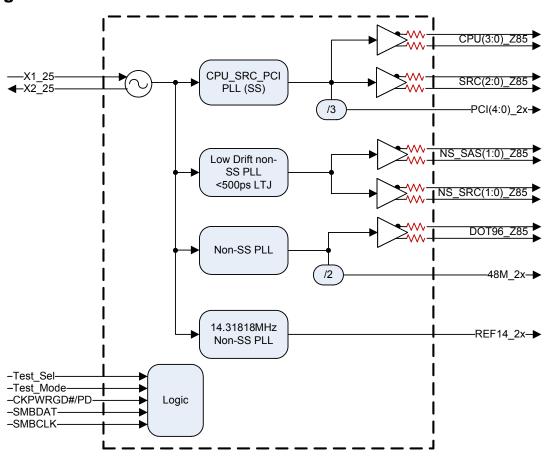


64VFQFPN Pin Descriptions (cont.)

PIN#	PIN NAME	TYPE	DESCRIPTION
39	NS_SAS1_Z85C	OUT	Complementary clock of low-power push-pull differential non-spreading SAS output.
39	NO_OAG1_Z000	001	Internally terminated to drive 85ohm transmission lines with no external components.
40	NS_SAS1_Z85T	OUT	True clock of low-power push-pull differential non-spreading SAS output. Internally
40		001	terminated to drive 85ohm transmission lines with no external components.
41	AVDD_NS_SAS	PWR	3.3V power for the non-spreading SAS/SRC PLL analog circuits.
42	GNDNS	PWR	Ground pin for non-spreading differential outputs and logic.
43	CPU0_Z85C	OUT	Complementary clock of low-power push-pull differential CPU output. Internally terminated
40	01 00_2000	001	to drive 85ohm transmission lines with no external components.
44	CPU0_Z85T	OUT	True clock of low-power push-pull differential CPU output. Internally terminated to drive
		001	85ohm transmission lines with no external components.
45	CPU1_Z85C	OUT	Complementary clock of low-power push-pull differential CPU output. Internally terminated
.0	01 01_2000	00.	to drive 85ohm transmission lines with no external components.
46	CPU1_Z85T	OUT	True clock of low-power push-pull differential CPU output. Internally terminated to drive
			85ohm transmission lines with no external components.
47	VDDCPU		3.3V power for the CPU outputs and logic
48	GNDCPU	PWR	Ground pin for CPU outputs and logic.
49	CPU2_Z85C OU		Complementary clock of low-power push-pull differential CPU output. Internally terminated
	0. 01_100	00.	to drive 85ohm transmission lines with no external components.
50	CPU2_Z85T OUT		True clock of low-power push-pull differential CPU output. Internally terminated to drive
			85ohm transmission lines with no external components.
51	CPU3_Z85C OI		Complementary clock of low-power push-pull differential CPU output. Internally terminated
			to drive 85ohm transmission lines with no external components.
52	CPU3_Z85T	OUT	True clock of low-power push-pull differential CPU output. Internally terminated to drive
			85ohm transmission lines with no external components.
53	VDDCPU		3.3V power for the CPU outputs and logic
54	SMBDAT		Data pin of SMBUS circuitry, 5V tolerant
55	SMBCLK		Clock pin of SMBUS circuitry, 5V tolerant
56	GND14		Ground pin for 14MHz output and logic.
57	AVDD14		Analog power pin for 14MHz PLL
58	VDD14	PWR	Power pin for 14MHz output and logic
			14.318 MHz reference clock capable of driving 2 loads/ TEST_SEL latched input to enable
59	vREF14_2x/TEST_SELLV	I/O	test mode. The TEST_SEL input is a low threshold input. See the Electrical Tables and the
			Test Clarification Table. This pin has a weak (~120Kohm) internal pull down.
60	GND14		Ground pin for 14MHz output and logic.
61	GNDXTAL		Ground pin for Crystal Oscillator.
	X1_25		Crystal input, Nominally 25.00MHz.
63	X2_25	OUT	Crystal output, Nominally 25.00MHz.
64	VDDXTAL		3.3V power for the crystal oscillator.
65	EPAD	GND	Epad should be connected to ground.



Block Diagram

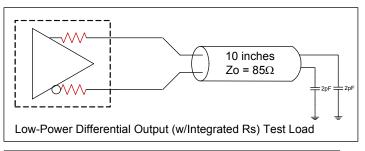


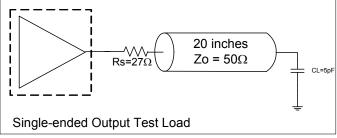


Power Supply and Test Loads

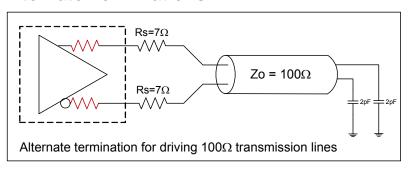
Power Group Pin Numbers

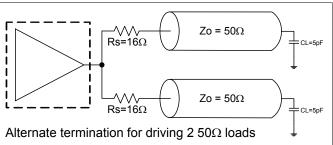
VFQF	PN	TSS	SOP	Description
VDD	GND	VDD	GND	Description
57	56	3	2	14MHz PLL Analog
58	60	4	6	REF14M Output and Logic
64	61	10	7	25MHz XTAL
2, 9	1, 8	12, 19	11, 18	PCI Outputs and Logic
10	12	20	22	48MHz Output and Logic
16	13	26	23	96MHz PLL Analog, Output and Logic
19, 27	22	29, 37	32	SRC Outputs and Logic
28	29	38	39	SRC PLL Analog
35	36	45	46	Non-Spreading Differential Outputs & Logic
41	42	51	52	NS-SAS/SRC PLL Analog
47, 53	48	57,63	58	CPU Outputs and Logic





Alternate Terminations





7



Functionality and CPU SAS Frequency Tables

932SQL450 Functionality

				NS_SAS			
CPU	SRC	PCI	REF	NS_SRC	DOT96	USB	
100	100	33.33	14.318	100.00	96.00	48.00	MHz

Spread Spectrum Control Functionality

SS_Enable	CPU, SRC &
(B1b0)	PCI
0	OFF
1	-0.50%

932SQL450 Power Down Functionality

CKPWRGD#/PD	Differential Outputs	Single- ended Outputs	Single- ended Outputs w/Latch	
1	Low/Low	Low	Low ¹	
0		Running		

^{1.} Single-ended outputs with a Latch will be Hi-Z until the first application of CKPWRGD#.

CPU/SRC/PCI Margining Table

Line	Byte6 Bit2 FS2	Byte6 Bit1 FS1	Byte6 Bit0 FS0	CPU Speed (MHz)	SRC (MHz)	PCI (MHz)
0	0	0	0	97.00	97.00	32.33
1	0	0	1	98.00	98.00	32.67
2	0	1	0	99.00	99.00	33.00
3	0	1	1	100.00	100.00	33.33
4	1	0	0	101.00	101.00	33.67
5	1	0	1	102.00	102.00	34.00
6	1	1	0	103.00	103.00	34.33
7	1	1	1	104.00	104.00	34.67

Default for 100MHz

NS_SAS Margining Table

Line	Byte5 Bit3 FS3	Byte5 Bit2 FS2	Byte5 Bit1 FS1	Byte5 Bit0 FS0	NS_xxx (MHz)
0	0	0	0	0	82.5
1	0	0	0	1	85.0
2	0	0	1	0	87.5
3	0	0	1	1	90.0
4	0	1	0	0	92.5
5	0	1	0	1	95.0
6	0	1	1	0	97.5
7	0	1	1	1	100.0
8	1	0	0	0	102.5
9	1	0	0	1	105.0
10	1	0	1	0	107.5
11	1	0	1	1	110.0
12	1	1	0	0	112.5
13	1	1	0	1	115.0
14	1	1	1	0	117.5
15	1	1	1	1	120.0

NOTE: Operation at other than the default entry is not guaranteed. These values are for margining purposes only.



Clock AC Tolerances

		NS_SAS,					
	CPU, SRC	NS_SRC	PCI	DOT96	48MHz	REF	
PPM tolerance	100	100	100	100	100	100	ppm
Cycle to Cycle Jitter	50	50	500	250	350	1000	ps
Spread	-0.50%	0.00%	-0.50%	0	0.00%	0.00%	%

Clock Periods-Outputs with Spread Spectrum Disabled

		Measurement Window								
SSC OFF	Center	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
	Freq. MHz	-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
CPU	100.000	9.94900		9.99900	10.00000	10.00100		10.05100	ns	1,2
SRC, NS_SAS, NS_SRC	100.000	9.94900		9.99900	10.00000	10.00100		10.05100	ns	1,2
PCI	33.333	29.49700		29.99700	30.00000	30.00300		30.50300	ns	1,2
DOT96	96.000	10.16563		10.41563	10.41667	10.41771		10.66771	ns	1,2
48MHz	48.000	20.48125		20.83125	20.83333	20.83542		21.18542	ns	1,2
REF	14.318	69.78429		69.83429	69.84128	69.84826		69.89826	ns	1,2

Clock Periods-Outputs with Spread Spectrum Enabled

	Center Freq. MHz		Measurement Window							
SSC ON		1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
		-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
CPU	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2
PCI	33.25	29.49718	29.99718	30.07218	30.07519	30.07820	30.15320	30.65320	ns	1,2
SRC	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy specifications are guaranteed with the assumption that the REF output is tuned to exactly 14.31818MHz.



General SMBus Serial Interface Information for 932SQL450

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) sends the byte count = X
- IDT clock will acknowledge
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will acknowledge each byte one at a time
- Controller (host) sends a Stop bit

	Index Blo	ck \	Write Operation
Controll	er (Host)		IDT (Slave/Receiver)
Т	starT bit		
Slave Add	ress D2 _(H)		
WR	WRite		
			ACK
Beginning	g Byte = N		
			ACK
Data Byte	Count = X		
			ACK
Beginnin	g Byte N		
			ACK
0		×	
0		X Byte	0
0		ë	0
			0
Byte N	+ X - 1		
			ACK
Р	stoP bit		

Read Address	Write Address
D3 _(H)	D2 _(H)

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will acknowledge
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends Byte 0 through Byte X (if X_(H) was written to Byte 8)
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- · Controller (host) will send a stop bit

	Index Block Read Operation							
Co	ntroller (Host)		IDT (Slave/Receiver)					
Т	starT bit							
Slave	Address D2 _(H)							
WR	WRite							
			ACK					
Begi	nning Byte = N							
			ACK					
RT	Repeat starT							
Slave	Address D3 _(H)							
RD	ReaD							
			ACK					
			Data Byte Count=X					
	ACK							
			Beginning Byte N					
	ACK							
		ē	0					
	0	X Byte	0					
	0	×	0					
	0							
			Byte N + X - 1					
N	Not acknowledge							
Р	stoP bit							



NOTE: Pin numbers refer to TSSOP

SMBus Table: Output Enable Register

Byte	0	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	2	4/25	DOT96 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 6	5	0/49	NS_SAS1 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 5	4	8/47	NS_SAS0 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 4	4	4/43	NS_SRC1 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 3	4	2/41	NS_SRC0 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 2	3	6/35	SRC2 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 1	3	4/33	SRC1 Enable	Output Enable	RW	Disable-Low/Low	Enable	1
Bit 0	3	0/31	SRC0 Enable	Output Enable	RW	Disable-Low/Low	Enable	1

SMBus Table: Output Enable Register

Byte	1 Pin #	Name	Control Function	Type	0	1	Default		
Bit 7	5	REF14_3x Enable	Output Enable	RW	Disable-Low	Enable	1		
Bit 6			RESERVED						
Bit 5		RESERVED							
Bit 4	62/61	CPU3	Output Enable	RW	Disable-Low/Low	Enable	1		
Bit 3	60/59	CPU2	Output Enable	RW	Disable-Low/Low	Enable	1		
Bit 2	56/55	CPU1	Output Enable	RW	Disable-Low/Low	Enable	1		
Bit 1	54/53	CPU0	Output Enable	RW	Disable-Low/Low	Enable	1		
Bit 0	CPU/SRC/ PCI	Spread Spectrum Enable	Spread Off/On	RW	Spread Off	Spread On	0		

SMBus Table: Output Enable Register

		<u> </u>						
Byte	2 Pin #	Name	Control Function	Type	0	1	Default	
Bit 7			RESERVE	D			0	
Bit 6			RESERVED					
Bit 5	13	PCI4 Enable	Output Enable	RW	Disable-Low	Enable	1	
Bit 4	14	PCI3 Enable	Output Enable	RW	Disable-Low	Enable	1	
Bit 3	15	PCI2 Enable	Output Enable	RW	Disable-Low	Enable	1	
Bit 2	16	PCI1 Enable	Output Enable	RW	Disable-Low	Enable	1	
Bit 1	17	PCI0 Enable	Output Enable	RW	Disable-Low	Enable	1	
Bit 0	21	48MHz Enable	Output Enable	RW	Disable-Low	Enable	1	

SMBus Table: Differential Amplitude Control

Byte	3 Pin #	Name	Control Function	Type	0	1	Default
Bit 7	•	CPU AMPLITUDE 1	CPU Vhigh	RW	00 = 700 mV	01 = 800mV	0
Bit 6		CPU AMPLITUDE 0	CFO Viligii	RW	10 = 900mV	11 = 1000mV	1
Bit 5		SRC AMPLITUDE 1	SDC Whigh	RW	00 = 700mV	01 = 800mV	0
Bit 4		SRC AMPLITUDE 0	SRC Vhigh	RW	10 = 900mV	11 = 1000mV	1
Bit 3		DOT96 AMPLITUDE 1	DOT96 Vhigh	RW	00 = 700 mV	01 = 800mV	0
Bit 2		DOT96 AMPLITUDE 0	DO 196 Viligii	RW	10 = 900mV	11 = 1000mV	1
Bit 1		NS-SAS/SRC AMPLITUDE 1	NC CAC/CDC Vbiab	RW	00 = 700 mV	01 = 800mV	0
Bit 0		NS-SAS/SRC AMPLITUDE 0	NS-SAS/SRC Vhigh	RW	10 = 900mV	11 = 1000mV	1

SMBus Table: Spread Amount Register

Byte 4	Pin #	Name	Control Function	Type	0	1	Default
Bit 7			RESERVE	D			0
Bit 6		RESERVED					
Bit 5		RESERVED					0
Bit 4		RESERVED					0
Bit 3			RESERVEI	D			0
Bit 2			RESERVEI)			0
Bit 1		SS AMOUNT[1]	Spread Amount (note	RW	00= -0.2%	10= -0.4%	1
Bit 0		SS AMOUNT[0]	B1b0 must be set to '1')	RW	01= -0.3%	11= -0.5%	1



SMBus Table: NS_SAS/NS_SRC Frequency Margining Table

			3					
Byte 5	Pin #	Name	Control Function	Type	0	1	Default	
Bit 7			RESERVE	D			0	
Bit 6			RESERVED					
Bit 5		RESERVED						
Bit 4			RESERVED					
Bit 3	-	FS3	Freq. Sel 3	RW			0	
Bit 2	-	FS2	Freq. Sel 2	RW	See NS_SAS/NS	_SRC Frequency	1	
Bit 1	-	FS1	Freq. Sel 1	RW	Tab	le.	1	
Bit 0	-	FS0	Freg. Sel 0	RW			1	

SMBus Table: Test Mode and CPU/SRC/PCI Frequency Select Register

Byte	6 Pin#	Name	Control Function	Type	0	1	Default	
Bit 7		Test Mode	Test Mode Type	RW	Hi-Z	REF/N	0	
Bit 6	ı	Test Select	Select Test Mode	RW	Disable	Enable	0	
Bit 5	•	RESERVED						
Bit 4	-	RESERVED						
Bit 3	•		RESERVE	D			0	
Bit 2	-	FS2	Freq. Sel 2	RW	Coo CDLI/CDC/I	OCI Fraguenov	0	
Bit 1	-	FS1	Freq. Sel 1	RW	See CPU/SRC/PCI Frequency Select Table		1	
Bit 0	•	FS0	Freq. Sel 0	RW			1	

Note: Internal Pull up on 100M_133M# pin will result in default CPU frequency of 100 MHz.

SMBus Table: Vendor & Revision ID Register

Byte 7	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	RID3		R	1 for B rev		0
Bit 6	-	RID2	REVISION ID	R			0
Bit 5	-	RID1	(1h forB rev)	R			0
Bit 4	-	RID0		R			1
Bit 3	-	VID3		R			0
Bit 2	-	VID2	VENDOR ID	R	0001 for	CC/IDT	0
Bit 1	-	VID1	VENDORID	R 0001 for ICS/IDT		0	
Bit 0	-	VID0		R			1

SMBus Table: Byte Count Register

Byte 8	B Pin#	Name	Control Function	Type	0 1		Default
Bit 7	-	BC7		RW	-	<u> </u>	0
Bit 6	-	BC6	1	RW	1		0
Bit 5	-	BC5		RW	Writing to this regis	ster will configure	0
Bit 4	-	BC4	Byte Count	RW	how many bytes v	vill be read back,	0
Bit 3	-	BC3	Programming b(7:0)	RW	default is	A bytes.	0
Bit 2	-	BC2		RW	(0 to	9	0
Bit 1	-	BC1		RW			0
Bit 0	-	BC0		RW			1

SMBus Table: Device ID Register

Byte 9	9 Pin #	Name	Control Function	Type	0	1	Default
Bit 7	·	DID7		R	•	-	0
Bit 6		DID6		R	-	-	1
Bit 5		DID5		R	-	-	0
Bit 4		DID4	Device ID	R	-	-	0
Bit 3		DID3	(45 hex)	R	-	-	0
Bit 2		DID2		R	-	-	1
Bit 1		DID1		R	-	-	0
Bit 0		DID0		R		-	1



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 932SQL450. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
3.3V Core Supply Voltage	VDDA				4.6	V	1,2
3.3V Logic Supply Voltage	VDD				4.6	V	1,2
Input Low Voltage	V_{IL}		GND-0.5			V	1
Input High Voltage	V_{IH}	Except for SMBus interface			V _{DD} +0.5V	V	1
Input High Voltage	V_{IHSMB}	SMBus clock and data pins			5.5V	V	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Case Temperature	Tc				110	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-Current Consumption

TA = T_{COM}: Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I _{DD3.3OP}	All outputs active CPU@100MHz, See Test Loads.		233	265	mA	
Powerdown Current	I _{DD3.3PDZ}			6	10	mA	

AC Electrical Characteristics-Differential LP-HCSL Outputs (CPU, SRC, NS_SAS, NS_SRC, DOT96)

 $TA = T_{COM}$; Supply Voltage VDD = 3.3 V +/-5%

r = 1 _{COM} , cupply voltage v _{BB} = 0.0 v 1/ 0/0							
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Duty Cycle	t _{DC}	Measured differentially, PLL Mode	45	49.9	55	%	1
Skew, Output to Output	t _{sk3SRC}	Across all SRC outputs, V _T = 50%		40	50	ps	1
Skew, Output to Output	t _{sk3CPU}	Across all CPU outputs, V _T = 50%		19	50	ps	1
Jitter, Cycle to cycle	+.	CPU, SRC, NS_SAS outputs		15	50	ps	1,3
officer, Cycle to Cycle	^l jcyc-cyc	DOT96 output		16	250	ps	1,3

¹Guaranteed by design and characterization, not 100% tested in production.

² Operation under these conditions is neither implied nor guaranteed.

 $^{^{2}}$ Zo=85 Ω (differential impedance).

³ Measured from differential waveform



Electrical Characteristics-Input/Supply/Common Parameters

 $TA = T_{COM}$: Supply Voltage VDD = 3.3 V +/-5%

$TA = T_{COM;}$ Supply Voltage							
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating Temperature	T _{COM}	Commmercial range	0		70	ŷ	
Input High Voltage	V _{IH}	Single-ended inputs, except SMBus, low threshold and tri-level inputs	2		V _{DD} + 0.3	٧	
Input Low Voltage	V_{IL}	Single-ended inputs, except SMBus, low threshold and tri-level inputs	GND - 0.3		0.8	٧	
Low Threshold Input- High Voltage	V_{IH_FS}	3.3 V +/-5%	0.7		V _{DD} + 0.3	٧	
Low Threshold Input- Low Voltage	V_{IL_FS}	3.3 V +/-5%	V _{SS} - 0.3		0.35	V	
	I _{IN}	Single-ended inputs, $V_{IN} = GND, V_{IN} = VDD$	-5		5	uA	
Input Current	I _{INP}	Single-ended inputs. V _{IN} = 0 V; Inputs with internal pull- up resistors V _{IN} = VDD; Inputs with internal pull- down resistors	-200		200	uA	
Input Frequency	Fi			25.00		MHz	2
Pin Inductance	L_{pin}				7	nΗ	1
	C _{IN}	Logic Inputs			5	pF	1
Capacitance	C _{OUT}	Output pin capacitance			5	pF	1
	C_{INX}	X1 & X2 pins			5	pF	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		0.4	1.8	ms	1,2
SS Modulation Frequency	f _{MODIN}	Allowable Frequency (Triangular Modulation)	30	31.5	33	kHz	1
Tdrive_PD#	t _{DRVPD}	Differential output enable after PD# de-assertion		98	300	us	1,3
Tfall	t_{F}	Fall time of control inputs			5	ns	1,2
Trise	t _R	Rise time of control inputs			5	ns	1,2
SMBus Input Low	V_{ILSMB}				0.8	V	
Voltage SMBus Input High Voltage	V _{IHSMB}		2.1		V _{DDSMB}	V	
SMBus Output Low Voltage	V _{OLSMB}	@ I _{PULLUP}			0.4	٧	
SMBus Sink Current	I _{PULLUP}	@ V _{OL}	4			mA	
Nominal Bus Voltage	V _{DDSMB}	3V to 5V +/- 10%	2.7		5.5	V	
SCLK/SDATA Rise Time	t _{RSMB}	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			100	kHz	

¹Guaranteed by design and characterization, not 100% tested in production.

 $^{^2\}mbox{Control}$ input must be monotonic from 20% to 80% of input swing.

³Time from deassertion until outputs are >200 mV



DC Electrical Characteristics—Differential LP-HCSL Outputs (CPU, SRC, NS_SAS, NS_SRC, DOT96)

 $T_A = T_{COM}$; Supply Voltage VDD = 3.3 V +/-5%

77 COW, 11 7 G							
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	dV/dt	Scope averaging on	1.5	2.9	4	V/ns	1,2,3
Slew rate matching	∆dV/dt	Slew rate matching, Scope averaging on		5	20	%	1,2,4
Voltage High	VHigh	Statistical measurement on single- ended signal using oscilloscope	660	774	850	mV	
Voltage Low	VLow	math function. (Scope averaging on)	-150	83	150	1110	
Max Voltage	Vmax	Measurement on single ended		918	1150	mV	7
Min Voltage	Vmin	signal using absolute value. (Scope	-300	-3		IIIV	7
Vswing	Vswing	Scope averaging off	300	1359		mV	1,2
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250	432	550	mV	1,5
Crossing Voltage (var)	Δ-Vcross	Scope averaging off		14	140	mV	1,6

 $^{^{1}}$ Guaranteed by design and characterization, not 100% tested in production. $Z_{O}=85\Omega$ (differential impedance).

Electrical Characteristics-48MHz

 $T_A = 0 - 70^{\circ}C$; Supply Voltage $V_{DD}/V_{DDA} = 3.3 \text{ V} + /-5\%$,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Output Impedance	R _{DSP}	$V_{O} = V_{DD}^{*}(0.5)$	12	21.7	55	Ω	1
Output High Voltage	V_{OH}	$I_{OH} = -1 \text{ mA}$	2.4			V	
Output Low Voltage	V _{OL}	$I_{OL} = 1 \text{ mA}$			0.55	V	
Clock High Time	T _{HIGH}	1.5V	8.094		10.036	ns	1
Clock Low Time	T _{LOW}	1.5V	7.694		9.836	ns	1
Edge Rate	t _{slewr/f_USB}	Rising/Falling edge rate	1		2.3	V/ns	1,2
Duty Cycle	d _{t1}	V _T = 1.5 V	45	50.4	55	%	1
Jitter, Cycle to cycle	t _{jcyc-cyc}	$V_{T} = 1.5 V$			350	ps	1

See "Power Supply and Test Loads" page for termination circuits

² Measured from differential waveform

³ Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all Vcross measurements in any particular system. Note that this is a subset of V_cross_min/max (V_cross absolute) allowed. The intent is to limit Vcross induced modulation by setting V_cross_delta to be smaller than

⁷ Includes overshoot and undershoot.

⁸ Measured from single-ended waveform

⁹ Measured with scope averaging off, using statistics function. Variation is difference between min and max.

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured between 0.8V and 2.0V



Electrical Characteristics-Phase Jitter Parameters

 $T_A = 0 - 70$ °C; Supply Voltage $V_{DD/}V_{DDA} = 3.3 \text{ V +/-5\%}$,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	INDUST. LIMIT	UNITS	Notes
	t _{jphPCleG1}	PCIe Gen 1		35	39	86	ps (p-p)	1,2,3, 6
		PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		1.52	1.84	3	ps (rms)	1,2,6
	t _{jphPCleG2}	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		2.19	2.42	3.1	ps (rms)	1,2,6
Phase Jitter	t _{jphPCleG3}	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.51	0.59	1	ps (rms)	1,2,4, 6
		QPI & SMI (100MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.25	0.37	0.5	ps (rms)	1,5,7
	t _{jphQPI_SMI}	QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.18	0.23	0.3	ps (rms)	1,5,7
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.15	0.19	0.2	ps (rms)	1,5,7
	t _{jphSAS12G}	SAS 12G		1.15	1.27	1.3	ps (rms)	1,5,8

¹ Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-PCI

 $T_A = 0 - 70$ °C; Supply Voltage $V_{DD/}V_{DDA} = 3.3 \text{ V +/-5}\%$,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Output Impedance	R _{DSP}	$V_{O} = V_{DD}^{*}(0.5)$	12	22	55	Ω	1
Output High Voltage	V _{OH}	$I_{OH} = -1 \text{ mA}$	2.4			V	
Output Low Voltage	V _{OL}	$I_{OL} = 1 \text{ mA}$			0.55	V	
Clock High Time	T _{HIGH}	1.5V	12			ns	1
Clock Low Time	T _{LOW}	1.5V	12			ns	1
Edge Rate	t _{slewr/f}	Rising/Falling edge rate	1	1.7	4	V/ns	1,2
Duty Cycle	d _{t1}	$V_{T} = 1.5 V$	45	50.4	55	%	1
Group Skew	t _{skew}	$V_{T} = 1.5 V$		197	500	ps	1
Jitter, Cycle to cycle	t _{icyc-cyc}	$V_{T} = 1.5 V$		45.52	500	ps	1

See "Power Supply and Test Loads" page for termination circuits

² See http://www.pcisig.com for complete specs

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ Subject to final radification by PCI SIG.

⁵ Calculated from Intel-supplied Clock Jitter Tool v 1.6.6

⁶ Applied to SRC outputs

⁷ Applies to CPU outputs

⁸ Applies to NS_SAS, NS_SRC outputs, Spread Off

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured between 0.8V and 2.0V



Electrical Characteristics-REF14M

 $T_A = 0 - 70$ °C; Supply Voltage $V_{DD/}V_{DDA} = 3.3 \text{ V } +/-5\%$,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
Output Impedance	R _{DSP}	$V_{O} = V_{DD}^{*}(0.5)$	12	21.7	55	Ω	1
Output High Voltage	V_{OH}	$I_{OH} = -1 \text{ mA}$	2.4			V	
Output Low Voltage	V_{OL}	$I_{OL} = 1 \text{ mA}$			0.55	V	
Clock High Time	T _{HIGH}	1.5V	27.5			ns	1
Clock Low Time	T _{LOW}	1.5V	27.5			ns	1
Edge Rate	t _{slewr/f}	Rising/Falling edge rate	1	1.9	4	V/ns	1,2
Duty Cycle	d _{t1}	$V_{T} = 1.5 V$	45	50.1	55	%	1
Jitter, Cycle to cycle	t _{jcyc-cyc}	$V_{T} = 1.5 V$		42	1000	ps	1

See "Power Supply and Test Loads" page for termination circuits

Test Clarification Table

Comments	Н	IW	S	W	
	TEST_SEL HW PIN	TEST_MOD E HW PIN	TEST ENTRY BIT B6b6	REF/N or HI-Z B6b7	OUTPUT
	0	Χ	0	Χ	NORMAL
Power-up w/ TEST_SEL = 1 (>0.7V) to enter test	1	0	Χ	0	HI-Z
mode. Cycle power to disable test mode.	1	0	Χ	1	REF/N
mode. Cycle power to disable test mode.	1	1	Χ	0	REF/N
	1	1	Χ	1	REF/N
	0	Х	1	0	HI-Z
If TEST_SEL HW pin is 0 during power-up, test mode can be selected through B6b6. If test mode is selected by B6b6, then B6b7 is used to select HI-Z or REF/N FS_B/TEST_Mode pin is not used. Cycle power to disable test mode.	0	X	1	1	REF/N

B6b6: 1= ENTER TEST MODE, Default = 0 (NORMAL OPERATION)

B6b7: 1= REF/N, Default = 0 (HI-Z)

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured between 0.8V and 2.0V



Recommended Crystal Characteristics (3225 package)

PARAMETER	VALUE	UNITS	NOTES
Frequency	25	MHz	1
Resonance Mode	Fundamental	-	1
Frequency Tolerance @ 25°C	±20	PPM Max	1
Frequency Stability, ref @ 25°C Over	+20	PPM Max	1
Operating Temperature Range	120	FFIVI IVIAX	'
Temperature Range (commerical)	0~70	°C	1
Temperature Range (industrial)	-40~85	°C	2
Equivalent Series Resistance (ESR)	50	Ω Max	1
Shunt Capacitance (C _O)	7	pF Max	1
Load Capacitance (C _L)	8	pF Max	1
Drive Level	0.3	mW Max	1
Aging per year	±5	PPM Max	1

Notes:

- 1. Fox Electronics 603-25-150 or equivalent
- 2. For I-temp, contact Fox Electronics at Foxonline.com

Marking Diagrams

ICS LOT YYWW 932SQL450BGL ICS
932SQL450BL
LOT
COO YYWW

64TSSOP

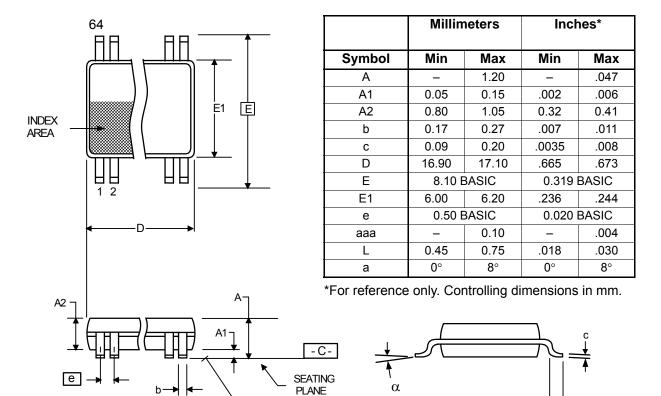
64VFQFPN

Notes:

- 1. "L" denotes Pb-free, RoHS compliant.
- 2. "LOT" denotes the lot number.
- 3. "YYWW" denotes the last two digits and week the part was assembled.
- 4. "COO" denotes the country of origin.
- 5. "B" denotes the device revision designator.
- 6. Bottom marking (TSSOP only): country of origin.



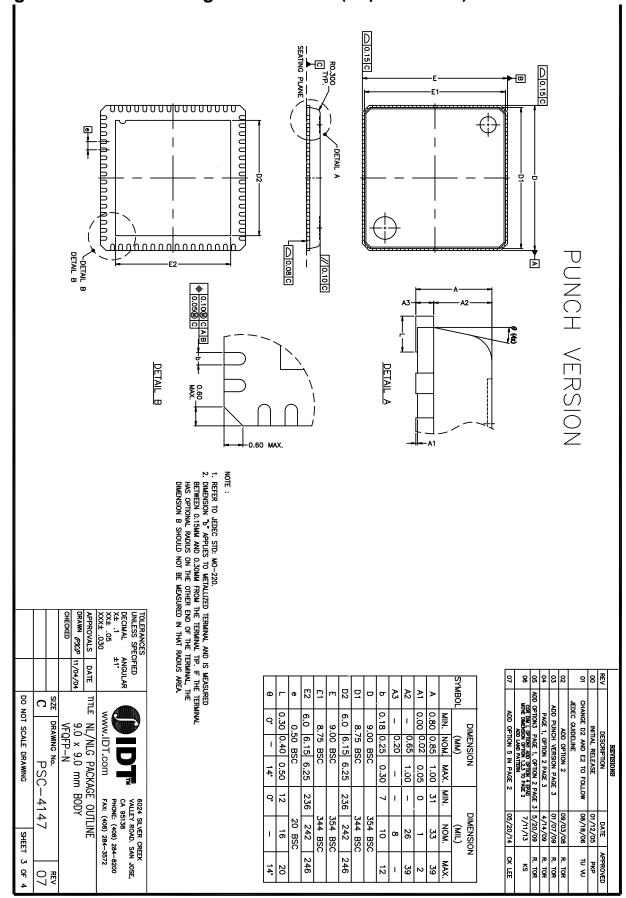
Package Outline and Package Dimensions (64-pin TSSOP)



aaa C



Package Outline and Package Dimensions (64-pin VFQFPN)





Package Outline and Package Dimensions (64-pin VFQFPN), cont.

NOTES:

1. ALL DIMENSION ARE IN mm. ANGLES IN DEGREES.
2. TOP DOWN VIEW. AS VIEWED ON PCB.
3. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
4. LAND PATTERN RECOMMENDATION PER IPC-7351B LP CALCULATOR.

EPAD 6.15 6.25 000000

			CHECKED	DRAWN PSP 11/04/04	APPROVALS	XX± .05 XXX± .030	DECIMAL /	TOLERANCES UNLESS SPECIFIED
				11/04/04	DATE		ANGULAR	IFIED
DO NO	C	SIZE			JITE	8		
DO NOT SCALE DRAWING	PSC-4147	DRAWING No.	VFQFP-N	9.0 x 9.0 mm BODY	TITLE NL/NLG PACKAGE OUTLINE	www.IDT.com Fax: (408) 284-3572	PHONE: (408) 284-8200	6024 SILVER CREEK VALLEY ROAD. SAN JOSE
SHEET					Æ) 284-357	108) 28 4 -	ÆR CREEK OAD. SAN
SHEET 4 OF 4	07	REV				72	B200	JOSE,

8		05	04	03	02		으	00	REV	
	COR DIM L OPTION1 ADD OPTION 4 EPAD MOVE DIMENSION OPTION 1,2,3 TO PAGE 2 ADD LAND PATTERN	ADD OPTION3 PAGE 1, OPTION 2 PAGE 3 5/20/09	PAGE 1, OPTION 2 PAGE 3	ADD PUNCH VERSION PAGE 3	ADD OPTION 2	JEDEC GUIDELINE	CHANGE D2 AND E2 TO FOLLOW	INITIAL RELEASE	DESCRIPTION	REVISIONS
	7/11/13	5/20/09	4/14/09	01/07/09	09/03/08		08/18/06	01/12/05	DATE	
	KS	R. TOR	R. TOR	R. TOR	R. TOR		Z Y	PKP	APPROVED	



Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
932SQL450BGLF	Tubes	64-pin TSSOP	0 to +70° C
932SQL450BGLFT	Tape and Reel	64-pin TSSOP	0 to +70° C
932SQL450BKLF	Tray	64-pin VFQFPN	0 to +70° C
932SQL450BKLFT	Tape and Reel	64-pin VFQFPN	0 to +70° C

[&]quot;LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

Revision History

Rev.	Issue Date	Who	Description	Page #
А	3/5/2014	RDW	1. Updated electrical table format and data to final. 2. Updated TEST_SEL pin description and TEST CLARIFICATION TABLE to indicate that this input is a low threshold input. 3. Updated TEST LOADS and added ALTERNATE TERMINATIONS diagrams. 4. Updated block diagram to latest format and updated pin names to match the pinout. 5. Updated front page text to latest format 6. Move to Final.	Various
В	3/6/2015	RDW	1. Corrected typo in Powerdown Current max limit. Max limit changed from 9mA to 10mA.	13

[&]quot;B" is the device revision designator (will not correlate with the datasheet revision).



Corporate Headquarters 6024 Silver Creek Valley Road San Jose, CA 95138 USA

Sales

1-800-345-7015 or 408-284-8200 Fax: 408-284-2775

www.IDT.com

Tech Support

email: clocks@idt.com

DISCLAIMER Integrated Device Technology, Inc. (IDT) and its subsidiaries reserve the right to modify the products and/or specifications described herein at any time and at IDT's sole discretion. All information in this document, including descriptions of product features and performance, is subject to change without notice. Performance specifications and the operating parameters of the described products are determined in the independent state and are not guaranteed to perform the same way when installed in customer products. The information contained herein is provided without representation or warranty of any kind, whether express or implied, including, but not limited to, the suitability of IDT's products for any particular purpose, an implied warranty of merchantability, or non-infringement of the intellectual property rights of others. This document is presented only as a guide and does not convey any license under intellectual property rights of IDT or any third parties.

IDT's products are not intended for use in applications involving extreme environmental conditions or in life support systems or similar devices where the failure or malfunction of an IDT product can be reasonably expected to significantly affect the health or safety of users. Anyone using an IDT product in such a manner does so at their own risk, absent an express, written agreement by IDT.

Integrated Device Technology, IDT and the IDT logo are registered trademarks of IDT. Product specification subject to change without notice. Other trademarks and service marks used herein, including protected names, logos and designs, are the property of IDT or their respective third party owners.

Copyright ©2015 Integrated Device Technology, Inc.. All rights reserved.